



## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Jimmy Liang, et al.

Art Unit: TBD

Serial No.: 10/032,907

Examiner: TBD

Filed: 12/28/01

Docket: TI-32508

For: Method and Apparatus for Flip Chip Device Assembly by Radiant Heating

## LETTER TO THE OFFICIAL DRAFTSPERSON

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that the above correspondence is being deposited  
with the U.S. Postal Service on 3-11-02  
as First Class Mail in an envelope addressed to: Assistant  
Commissioner for Patents, Washington, D.C. 20231.

Karen Vertz  
Karen Vertz

3-11-02  
Date

Assistant Commissioner for  
Patents  
Washington, D. C. 20231

Dear Sir:

Enclosed are **FOUR (4)** sheets of formal drawings for the above-referenced case.  
Please charge any necessary fees to Deposit Account No. 20-0668 of Texas Instruments  
Incorporated. This sheet is enclosed in triplicate.

Texas Instruments Incorporated  
P.O. Box 655474 M/S 3999  
Dallas, Texas 75265  
(214) 939-8651

Respectfully submitted,

Gary C. Honeycutt  
Gary C. Honeycutt  
Reg. No. 20,250  
Attorney for Applicants